



YUSO-131

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of
Hsieh et al.

) Art Unit: 2818
)

Serial No.: 10/052,989

) Examiner: David Vu
)

Filing Date: November 9, 2001

For: Formation of Electroplate
Solder on an Organic Circuit
Board for Flip Chip Joints and
Board to Board Solder Joints

Mail Stop After Final
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

OK to enter

AMENDMENT TO FINAL OFFICE ACTION DATED MARCH 3, 2006

DV

In response to the Final Office Action dated March 3, 2006, please enter and

consider the following amendments and remarks: